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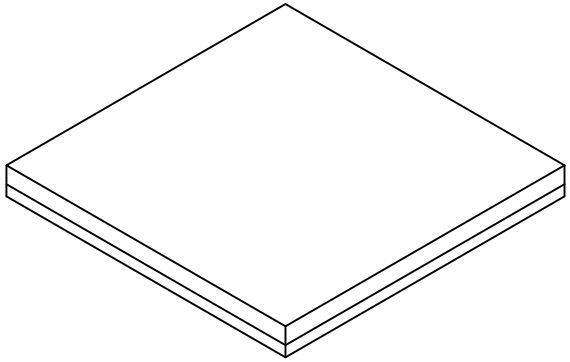
REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C02840	1/05/98	EKABI	JBW
01	UPDATED TO STANDARDS, DCN C04483	08/28/98	E.B.	HLE



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 100.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 10 X 10.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL	ANGULAR
X.X ±0.10	±1°
X.XX ±0.05	
X.XXX ±0.03	

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

PROJECTION

APPROVALS		DATE
DRAWN	HOAI LE	12/17/97
CHECKED	D. GASTELUM	12/17/97
ENG'R	T. PANCZAK	12/17/97
RELEASED	M. ANTONIO	12/23/97

ANAM Industrial Co., LTD.
Sungdong-Ku, Seoul, Korea

AMKOR Electronics, Inc.
Chandler, Arizona, USA

amkor anam

TITLE: PACKAGE OUTLINE – CABGA 100, 10.00mm X 10.00mm, 2 LAYER, 0.80mm PITCH, LAMINATE SUBSTRATE, AAP

SIZE	SID NUMBER	DWG NUMBER	REV
B	N/A	73202	01

STRIP DWG NUMBER/REV	CUST CODE	SCALE: 8:1	SHEET 1 OF 3
N/A	N/A		

ZF00004 REV E